Kizen™

NEXT GENERATION HOTMELT ADHESIVES FOR CARDBOARD PACKAGING

Kizen™

Cutting edge adhesive solutions, driven by Arkema expertise.

From a unique water-white hotmelt technology, KIZEN™ have been designed for ease of use and strong bond performance for cardboard packaging.

Kizen™ FORCE

DIFFICULT SUBSTRATES	
Application temperature	160-180° C
Viscosity	approx. 1250 mPa.s
Softening point	approx. 109° C

Kizen™ ICE

DEEP-FREEZE APPLICATIONS	
Application temperature	160-180° C
Viscosity	approx. 1350 mPa.s
Softening point	approx. 107° C

Kizen™ HEAT

TEMPERATURE RESISTANCE	
Application temperature	160-180° C
Viscosity	approx. 2300 mPa.s
Softening point	approx. 107° C

COMFORT

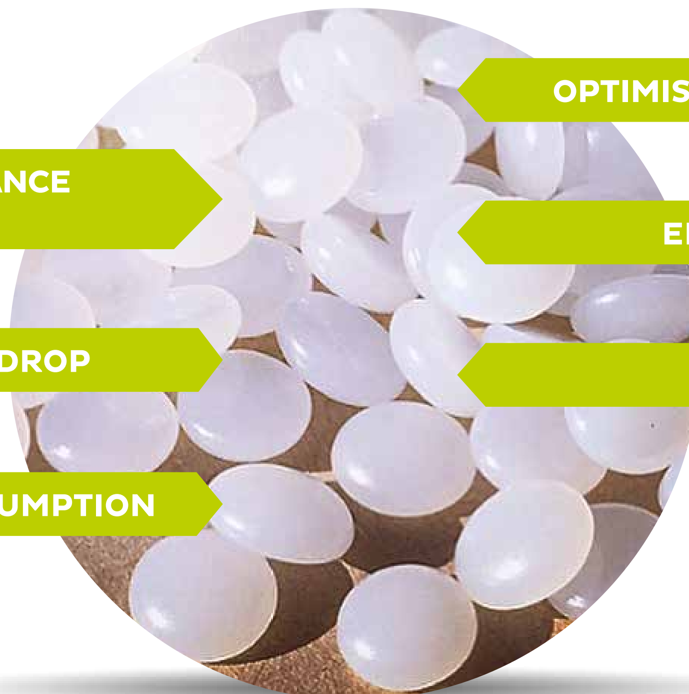
- Plug & Play** switch / Excellent chemical compatibility
- Free flowing / Room temperature tack-free pellets
- Clean hoses and nozzles / Thermal stability
- Ultra precise drop / Clean cut adhesive
- Improved atmosphere / Low odour

SECURITY

- Reinforced supply availability and stability / Bostik integration to Arkema
- Fall prevention / Flat pellets
- Enhanced ergonomics / Light and easy prehension packaging
- Cleaner atmosphere / Low fuming

EFFICIENCY

- Minimal adhesive consumption / Coating weight reduction (up to -50%*)
- Increased productivity / Reduction of line stops and fast setting time
- Investment-free Plug & Play** implementation / Excellent chemical compatibility
- More reliable closing / High performance bonds (up to +60%*)



OPTIMISED MAINTENANCE

HIGH PERFORMANCE BONDS

ENHANCED SAFETY

ULTRA PRECISE DROP

EASY SWITCH

REDUCED CONSUMPTION

* Benchmark study on conventional adhesives and substrates
** Plug & Play : compatibility of adhesive and equipment

comfort

security

efficiency

FOR OPTIMAL PRODUCTIVITY AND PEACE OF MIND

Kizen™

www.bostik.com/kizen

ARKEMA

An Arkema company

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